

# High Performance Thermal Interface Solutions

Thermal Interface Pads for Power Electronics



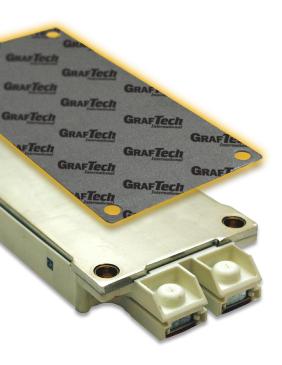


Avoid Expensive Dispensing Equipment and Messy Rollers



Eliminate Dry-Out and Pump-Out Failures

# LIBERATE YOURSELF FROM GREASE





# **Dispense-Free Manufacturing**

- Pad form factor
- Easily integrates into any size production line
- Eliminate re-torque process to prevent torque loss



### **Reliable, Consistent Thermal Performance**

- Unaffected by extreme temperatures
- Unlimited performance lifetime



#### **Residue-Free Repairs**

 Eliminates grease clean-up and application processes required to replace failed modules



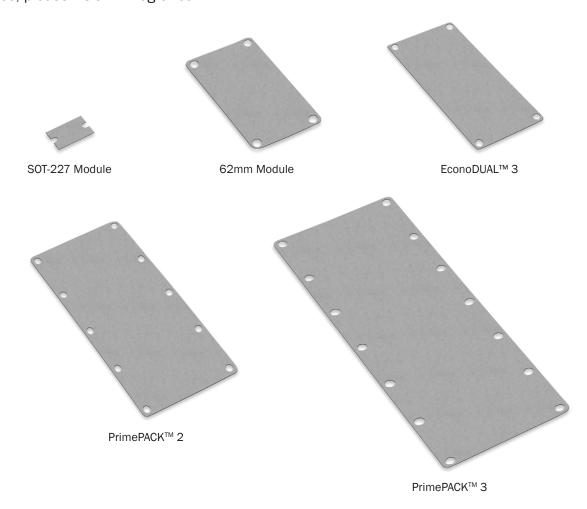
# HITHERM™ HT-C3200 Thermal Interface Material

HITHERM™ HT-C3200 Thermal Interface Material (TIM) is the first of its kind, compressible graphite sheet with thermal performance that matches traditional thermal grease without pump-out and dry-out failure modes.

This breakthrough material was developed to address the reliability challenges of mission critical applications in extreme temperature environments and harsh duty cycles.

# HT-C3200 TIM Portfolio

Most popular thermal interfaces shown below. For a complete list or to inquire about a custom device, please visit www.egraf.com.



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#### **Environmentally Friendly**

- RoHS, REACH compliant
  - Contains no hazardous materials
- Chemically inert to almost any substance
- Easy disposal of waste
- Contains no hazardous materials







**Redefining limits** 



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